



REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

NOTES:

MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0.

Contact: Copper Alloy

Shell: STAINLESS

PLATING :

TERMINAL:

CONTACT AREA: GOLD FLASH.

SOLDER AREA: MATTE TIN PLATED.

UNDER PLATE: NICKEL.

SHELL: NICKEL OVER ALL.

SOLDER AREA: GOLD FLASH.

Electrical:

Current Rating :0.5mA max.

Voltage Rating :50V DC MAX

Ambient Temperature Range :-20° C~+85° C

Storage Temperature Range :-40° C~+70° C

Ambient Humidity Range :95% R.H. Max.

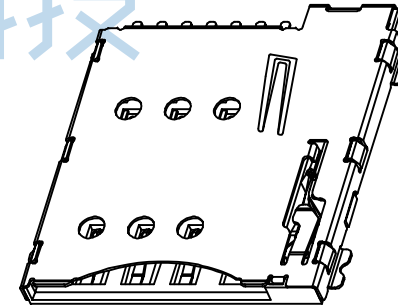
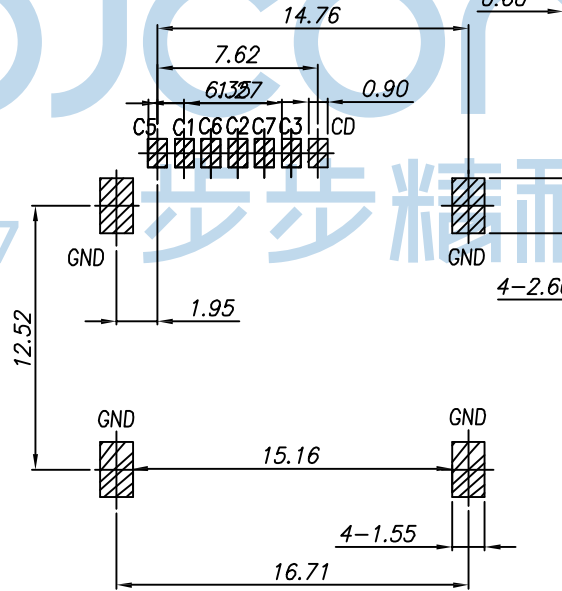
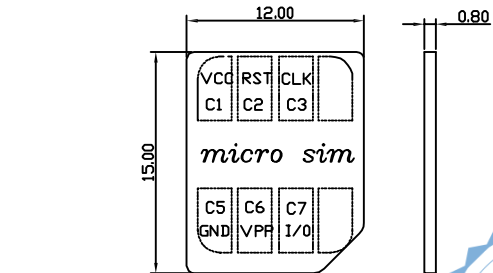
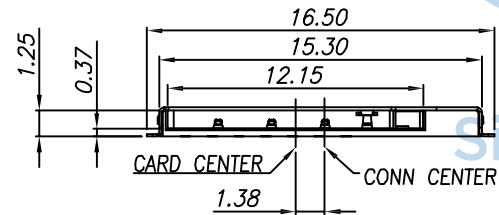
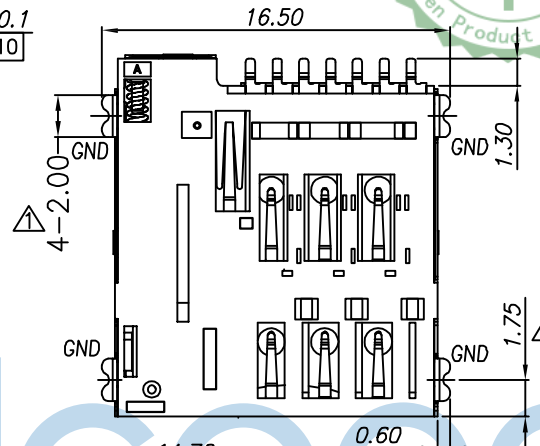
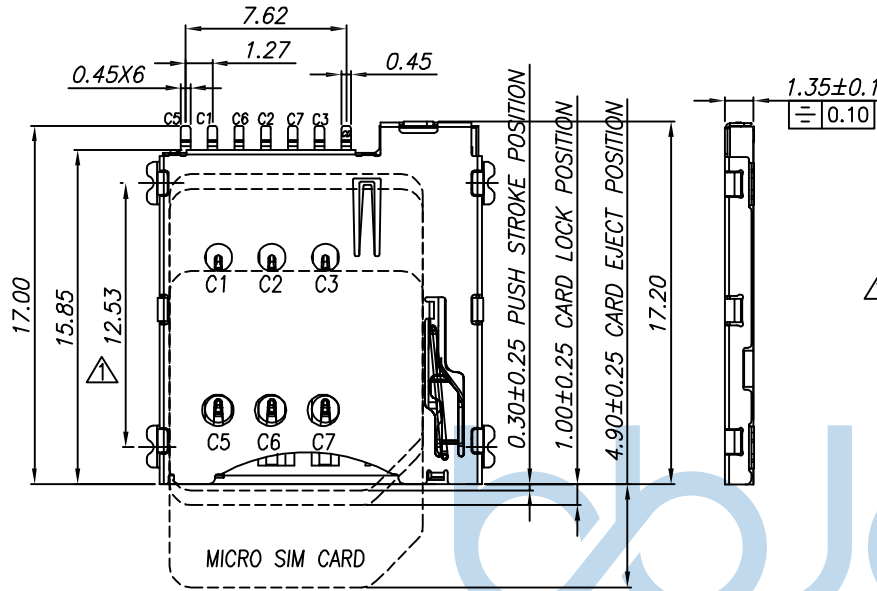
Contact Resistance:100mΩmax.

Insulation Resistance:1000MΩmin./250V DC

Dielectric Withstanding Voltage:500V AC

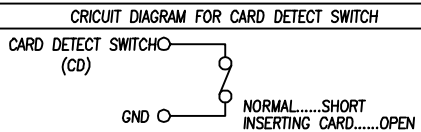
Mating Cycles:5,000 Insertions

Temperature: 260° C ±5°



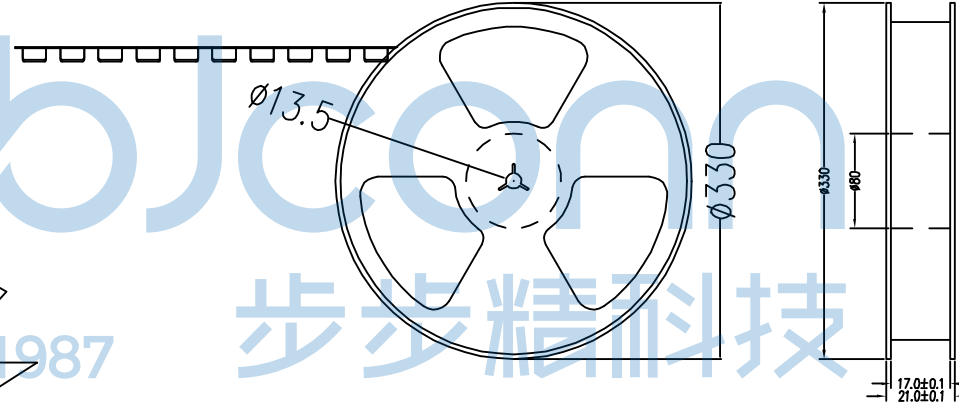
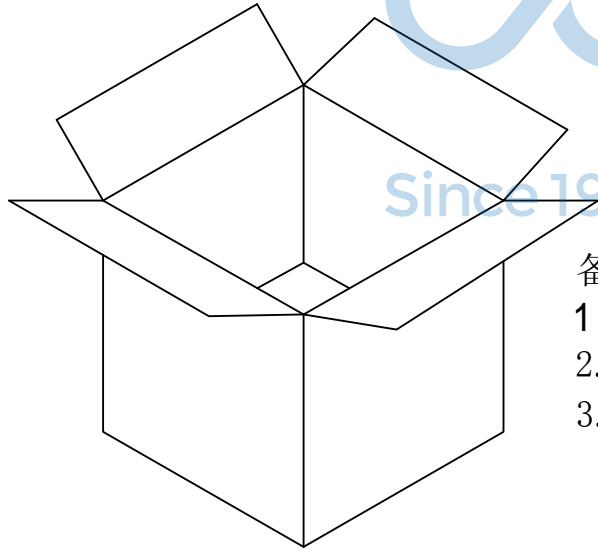
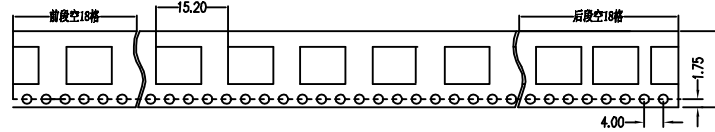
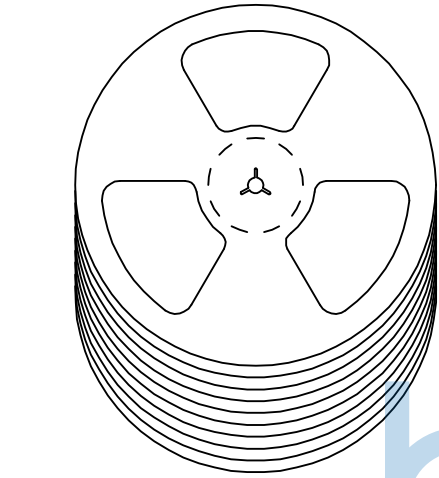
SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

■ CIRCUIT TRACE KEEP OUT AREA
■ SMT SOLDER AREA
THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



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NAME:	卡座 SIM SM05-135-0012 6P+CD PIN H=1.35 贴片 无柱 编带		
APPD.	JM_Zheng	PJ. NO.:	CD.02.02-02-0005
CHKD.	LYX	SIZE:	A4 DRW NO.:
PDWG.NO:	0214-1	FINISH:	SEE NOTES
DR.	TSP	MAT'L.:	SEE NOTES
		SCALE:	N/A
		REV.:	A0
		UNIT:	mm
		PAGE:	1/2

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



备注:

1. 包装数量：1000/PCS/卷，10卷/箱
2. 包装袋长度：每卷前后各空10-20个空格，中间包装。
3. 材质：
载体：聚丙烯（PS），
上带：聚乙烯（PET），
卷盘：聚苯乙烯。

纸箱规格：345*345*23MM

纸箱规格：345*345*35MM

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CHKD.	LYX	SCALE: N/A		REV.: A0	UNIT: mm
PDWG.NO:	0214-1	DR.	TSP	PAGE: 2/2	